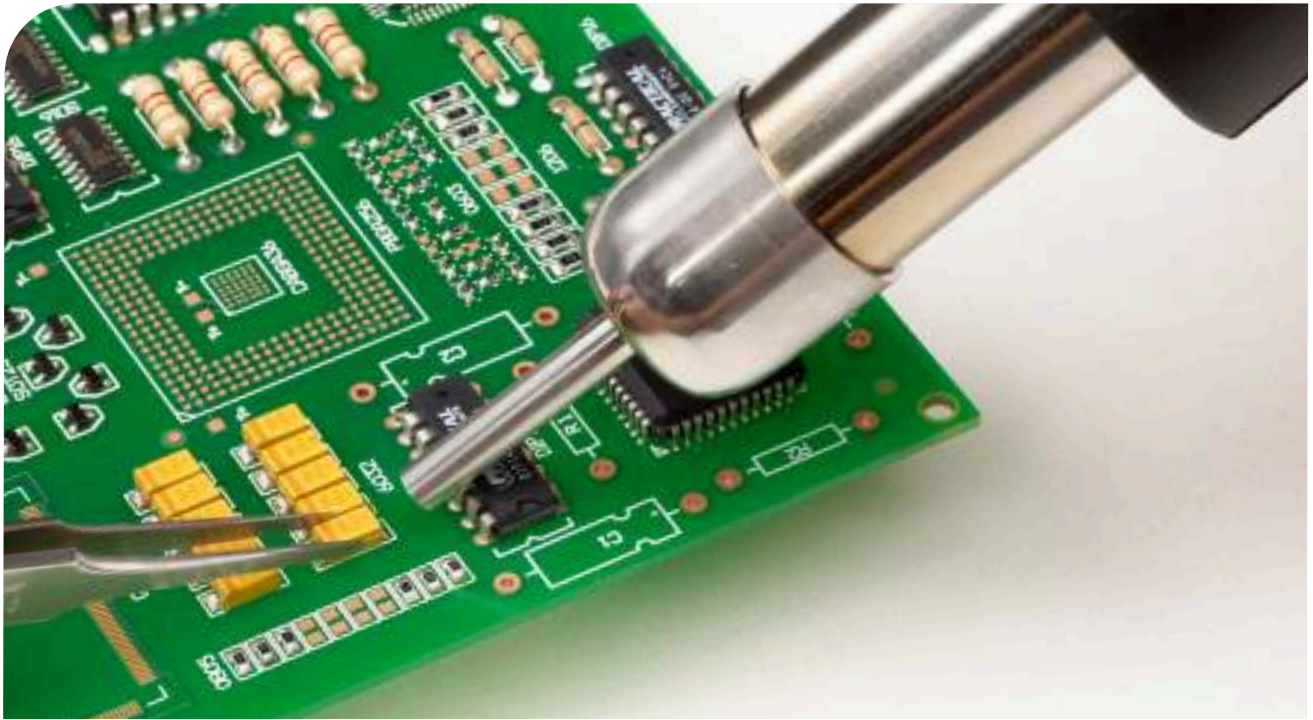


HCT-900 Hand Held Convection Tool



Versatile Hot Air Tool for Soldering and Desoldering Applications

The HCT-900 Hand Held Convection Tool offers a low cost, versatile rework solution for a wide variety of production and rework application challenges. It has a simple, compact robust design comprising of analog controls for both airflow and heat. A closed loop feedback circuit controls the temperature allowing the desired temperature to be achieved and maintained regardless of changes in the volume of airflow.

The HCT-900 can be used for the removal and refitting of electronic components, including lead-free, from 0201 up to 304 pin QFP. It is also effective at reworking pin in-hole devices such as sockets and connectors. And, using it with solder braid and flux is a fast and efficient way to remove solder shorts and splashes. It can also be used in plastic applications such as applying shrink wrap to components or the formation of plastic rivets.

The unique low noise air pump (less than 45 db) provides precise airflow control for the most demanding applications. The “power off” cool down function retains airflow through the hand piece while the unit powers down, providing efficient heater cooling and reducing thermal stress.

The HCT-900 is fully ESD compliant.



Part No.	Description
HCT-900-11	115 VAC, Hand Held Convection Tool
HCT-900-21	230 VAC, Hand Held Convection Tool
HCT-900-10	100 VAC, Hand Held Convection Tool

Nozzle Selection

The HCT-900 is supplied with a standard single jet H-D50 (0.2", 5.0 mm) nozzle. In addition two rework nozzle kits, predefined for specific applications, are available, as well as a full selection of nozzles.

Part No.	Description
NZKT-1	Nozzle Kit for Chip Resistors, SOIC & TSOP Packages. Includes (one each): <ul style="list-style-type: none"> • H-D25 • H-SL16 • H-SL28 • H-SOJ40 • H-TS48
NZKT-2	Nozzle Kit for PLCC, QFP & BQFP packages. Includes (one each): <ul style="list-style-type: none"> • H-P20 • H-P44 • H-P84 • H-Q1420 • H-Q2626

Model	Chip Type	A mm (in)	B mm (in)
PLCC, BQFP, QFP			
H-P20	PLCC-20	11.9 (0.47")	11.9 (0.47")
H-P28	PLCC-28	14.5 (0.57")	14.5 (0.57")
H-P32	PLCC-32	16.9 (0.67")	14.3 (0.56")
H-P44	PLCC-44	19.5 (0.77")	19.5 (0.77")
H-P52	PLCC-52	22.0 (0.86")	22.1 (0.87")
H-P68	PLCC-68	27.0 (1.06")	27.2 (1.07")
H-P84	PLCC-84	32.4 (1.28")	32.4 (1.28")
H-Q07	QFP-48	8.4 (0.33")	8.4 (0.33")
H-Q10	QFP-44	13.4 (0.53")	13.4 (0.53")
H-Q14	QFP-52,80	17.3 (0.68")	17.3 (0.68")
H-Q1420	QFP-64,80,100	23.4 (0.92")	18.1 (0.71")
H-Q28	QFP-120,128,144,160	31.2 (1.23")	31.2 (1.23")
H-BQ23	BQFP-100	22.4 (0.88")	22.4 (0.88")
H-Q3232	QFP-240	34.5 (1.36")	34.5 (1.36")
H-BQ38	BQFP-196	37.7 (1.48")	37.7 (1.48")
H-Q2626	QFP-208	29.8 (1.17")	29.8 (1.17")
SOIC, TSOP			
H-S16	SOIC 14,16	6.8 (0.27")	10.2 (0.4")
H-SL16	SOL 14,16	10.6 (0.41")	10.8 (0.43")
H-SL20	SOL 20,20J	10.6 (0.41")	13.3 (0.52")
H-SL24	SOL 24,24J	10.6 (0.41")	15.9 (0.63")
H-SL28	SOL 28	10.6 (0.41")	18.4 (0.72")
H-SL44	SOL 44	16.0 (0.41")	27.9 (1.1")
H-SOJ32	SOJ 32	13.5 (0.53")	20.6 (0.81")
H-SOJ40	SOJ 40	13.5 (0.53")	25.4 (1.0")
H-TS24	TSOP 20-24	17.0 (0.67")	7.1 (0.28")
H-TS32	TSOP 28-32	21.0 (0.83")	9.1 (0.36")
H-TS40	TSOP 40	21.0 (0.83")	10.8 (0.43")
H-TS48	TSOP 48	21.0 (0.83")	13.3 (0.52")
H-TSW24	TSOP 20-24	10.2 (0.4")	18.4 (0.72")
H-TSW44	TSOP 24-28/40-44	12.7 (0.5")	19.8 (1.78")
CHIP & SOT			
Model	Ø A (mm)		
H-D25	2.5 (0.1")		
H-D50	5.0 (0.2")		
H-D120	12.0(0.47")		

Specifications

Input Line Voltage	115 VAC HCT-900-11 230 VAC HCT-900-21 100 VAC HCT-900-10
Power	320 W
Air Pump Type	Diaphragm
Air Flow	6-25 l/min.
Control Temperature	100°C – 500°C (212°F – 932°F)
Dimensions w x l x h	6.7"x 8.7" x 5.5" inches, 170 x 210 x 140 mm
Noise Level	Less than 46 dBA
Surface Resistivity	Unit: 10 ⁵ Ω – 10 ⁶ Ω. Hand-piece & tube: 10 ⁷ Ω – 10 ¹¹ Ω
Weight	10.4 lbs. (4.7 kg.)
Certification / Approvals	cTUVus, CE